

APPLICATION OF CONDUCTIVE VIA OR TRENCH FOR INTRA MODULE EMI SHIELDING

ABSTRACT

5 A packaged semiconductor module comprises a substrate having a ground plane,
an electronic device mounted on a surface of the substrate, a bond pad disposed on the
surface of the substrate and electrically connected to the ground plane, a mold compound
covering the electronic device, a conductive post disposed on a side of the electronic
device, the conductive post extending from the bond pad and at least partially through the
10 mold compound, and a conductive layer disposed on the mold compound and electrically
coupled to the conductive post and to the ground plane, the conductive post, the
conductive layer, and the ground plane together forming the integrated electromagnetic
interference shield, the conductive post extending from the bond pad to the conductive
layer in a direction perpendicular to a plane defined by the surface of the substrate.

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[FIG. 1]